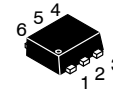


Dual Switching Diode

BAS16DXV6



SOT-563
CASE 463A
PLASTIC

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_A = 25°C)

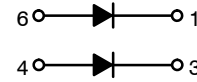
| Rating | Symbol | Max | Unit |
|---|------------------------|-----|------|
| Continuous Reverse Voltage | V _R | 100 | V |
| Recurrent Peak Forward Current | I _F | 200 | mA |
| Peak Forward Surge Current Pulse Width = 10 μs | I _{FM(surge)} | 500 | mA |

THERMAL CHARACTERISTICS

| Characteristic (One Junction Heated) | Symbol | Max | Unit |
|---|-----------------------------------|-------------|-------------|
| Total Device Dissipation (Note 1) T _A = 25°C Derate above 25°C | P _D | 357 2.9 | mW mW/°C |
| Thermal Resistance, Junction-to-Ambient (Note 1) | R _{θJA} | 350 | °C/W |
| Characteristic (Both Junctions Heated) | Symbol | Max | Unit |
| Total Device Dissipation (Note 1) T _A = 25°C Derate above 25°C | P _D | 500 4.0 | mW mW/°C |
| Thermal Resistance, Junction-to-Ambient (Note 1) | R _{θJA} | 250 | °C/W |
| Junction and Storage Temperature | T _J , T _{stg} | -55 to +150 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-4 @ Minimum Pad



MARKING DIAGRAM



A6 = Specific Device Code
M = Date Code
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|---------------|----------------------|-----------------------|
| BAS16DXV6T1G | SOT-563 (Pb-Free) | 4000 / Tape & Reel |
| SBAS16DXV6T1G | SOT-563 (Pb-Free) | 4000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

BAS16DXV6

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit |
|---|-----------------|------------------|----------------------------|------|
| Forward Voltage (I _F = 1.0 mA) (I _F = 10 mA) (I _F = 50 mA) (I _F = 150 mA) | V _F | – – – – | 715 855 1000 1250 | mV |
| Reverse Current (V _R = 100 V) (V _R = 75 V, T _J = 150°C) (V _R = 25 V, T _J = 150°C) | I _R | – – – | 1.0 50 30 | μA |
| Capacitance (V _R = 0, f = 1.0 MHz) | C _D | – | 2.0 | pF |
| Reverse Recovery Time (I _F = I _R = 10 mA, R _L = 50 Ω) (Figure 1) | t _{rr} | – | 6.0 | ns |
| Stored Charge (I _F = 10 mA to V _R = 6.0 V, R _L = 500 Ω) (Figure 2) | Q _S | – | 45 | PC |
| Forward Recovery Voltage (I _F = 10 mA, t _r = 20 ns) (Figure 3) | V _{FR} | – | 1.75 | V |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

BAS16DXV6

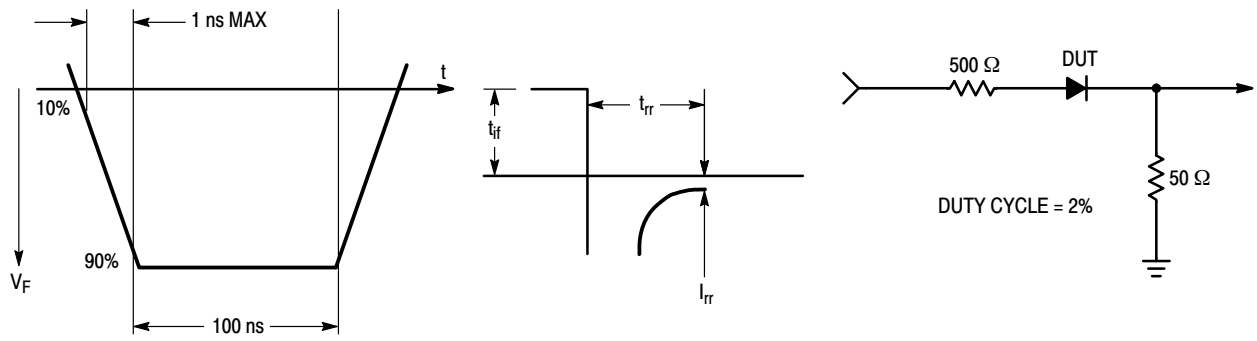


Figure 1. Reverse Recovery Time Equivalent Test Circuit

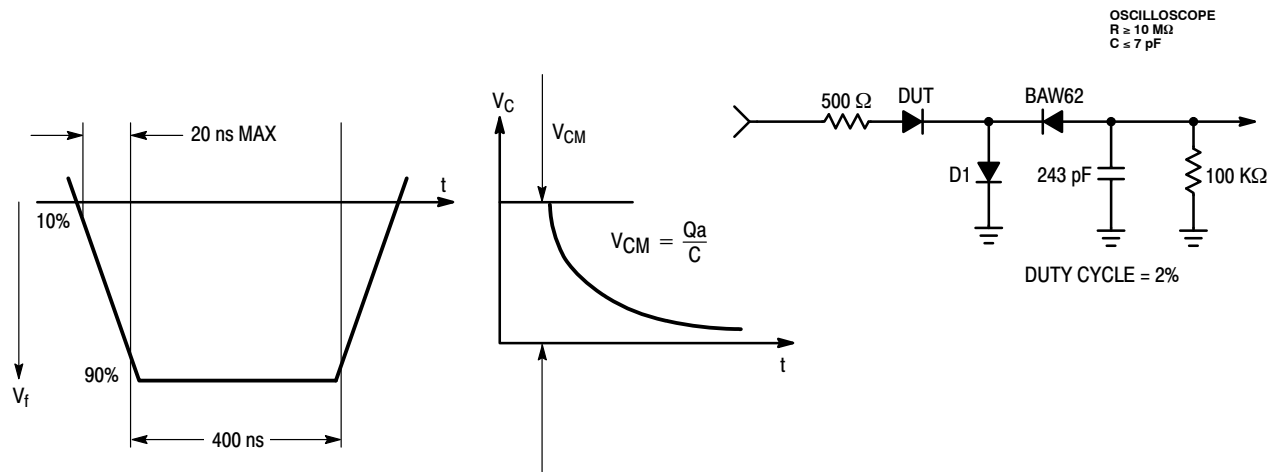


Figure 2. Stored Charge Equivalent Test Circuit

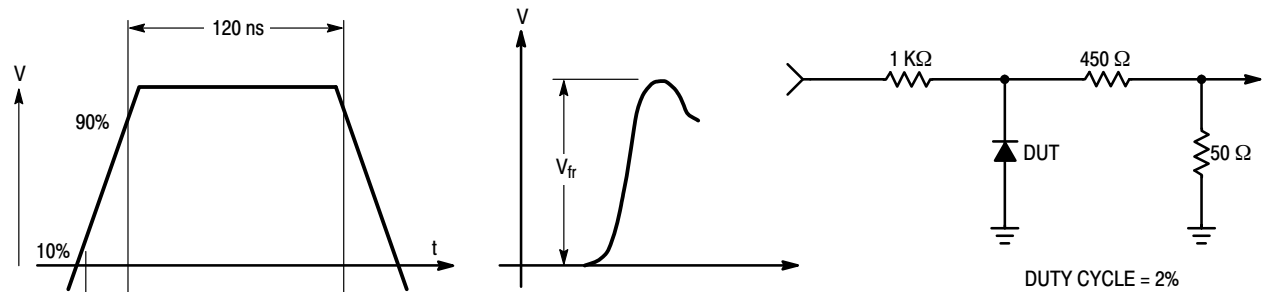


Figure 3. Forward Recovery Voltage Equivalent Test Circuit

BAS16DXV6

TYPICAL CHARACTERISTICS

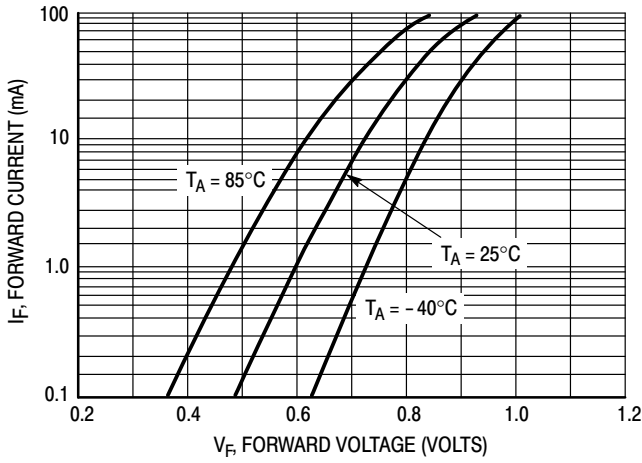


Figure 4. Forward Voltage

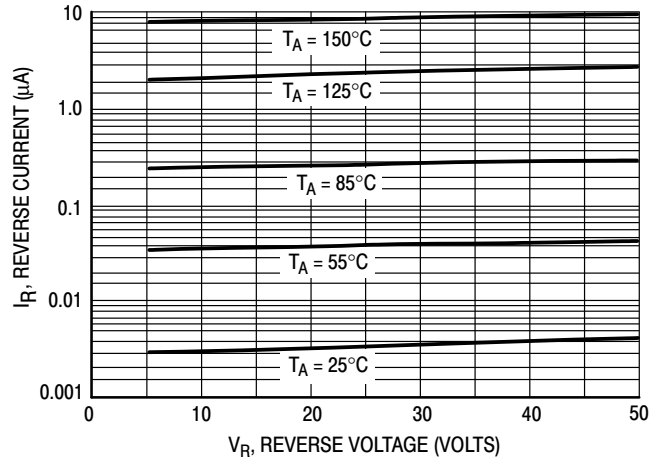


Figure 5. Leakage Current

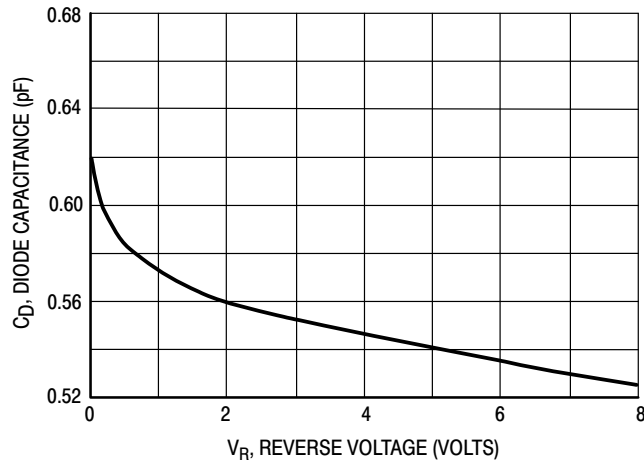


Figure 6. Capacitance

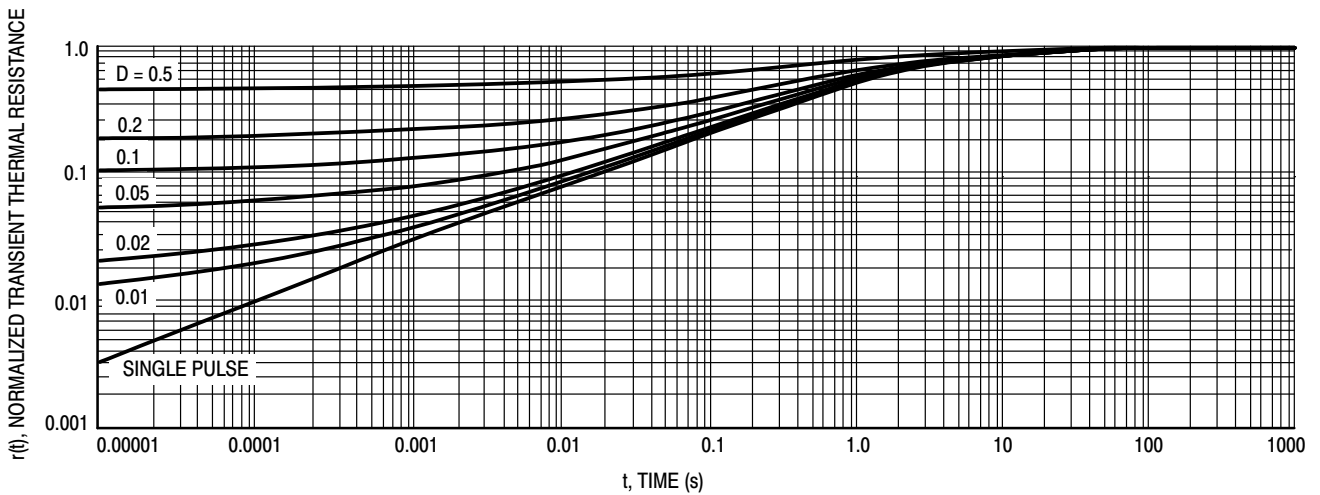


Figure 7. Normalized Thermal Response

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

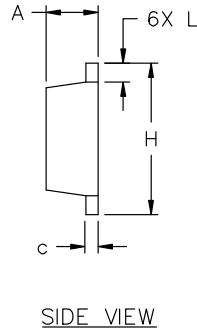
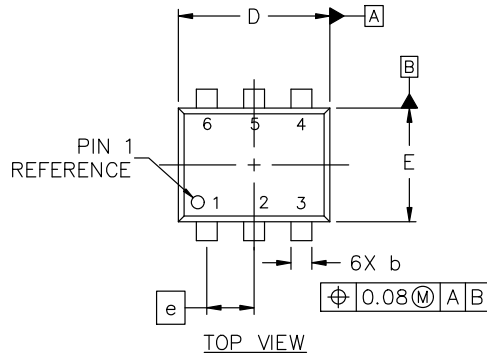


SOT-563-6 1.60x1.20x0.55, 0.50P
CASE 463A
ISSUE J

DATE 15 FEB 2024

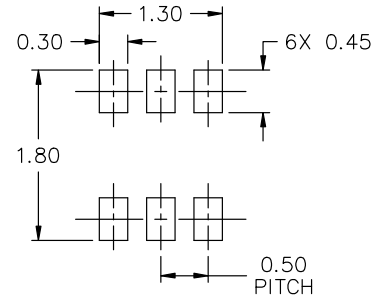
NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.



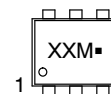
| DIM | MILLIMETERS | | |
|-----|-------------|------|------|
| | MIN. | NOM. | MAX. |
| A | 0.50 | 0.55 | 0.60 |
| b | 0.17 | 0.22 | 0.27 |
| c | 0.08 | 0.13 | 0.18 |
| D | 1.50 | 1.60 | 1.70 |
| E | 1.10 | 1.20 | 1.30 |
| e | 0.50 BSC | | |
| H | 1.50 | 1.60 | 1.70 |
| L | 0.10 | 0.20 | 0.30 |

- | | | |
|--|---|--|
| <p>STYLE 1: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2 6. COLLECTOR 1</p> | <p>STYLE 2: PIN 1. EMITTER 1 2. EMITTER 2 3. BASE 2 4. COLLECTOR 2 5. BASE 1 6. COLLECTOR 1</p> | <p>STYLE 3: PIN 1. CATHODE 1 2. CATHODE 1 3. ANODE/ANODE 2 4. CATHODE 2 5. CATHODE 2 6. ANODE/ANODE 1</p> |
| <p>STYLE 4: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR</p> | <p>STYLE 5: PIN 1. CATHODE 2. CATHODE 3. ANODE 4. ANODE 5. CATHODE 6. CATHODE</p> | <p>STYLE 6: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE</p> |
| <p>STYLE 7: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. ANODE 6. CATHODE</p> | <p>STYLE 8: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN</p> | <p>STYLE 9: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1</p> |
| <p>STYLE 10: PIN 1. CATHODE 1 2. N/C 3. CATHODE 2 4. ANODE 2 5. N/C 6. ANODE 1</p> | <p>STYLE 11: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2</p> | |



* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



- XX = Specific Device Code
- M = Month Code
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

| | | |
|-------------------------|--|--|
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| DESCRIPTION: | SOT-563-6 1.60x1.20x0.55, 0.50P | PAGE 1 OF 1 |

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